

Surface-Mount TMBS[®] (Trench MOS Barrier Schottky) Rectifier

eSMP[®] Series



Top View

Bottom View

SlimSMAW (DO-221AD)

Cathode Anode

DESIGN SUPPORT TOOLS

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PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	3 A
V_{RRM}	120 V
I_{FSM}	60 A
V_F at $I_F = 3$ A (125 °C)	0.61 V
T_J max.	175 °C
Package	SlimSMAW (DO-221AD)
Circuit configuration	Single

FEATURES

- Low-profile package
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
 - Automotive ordering code: base P/NHM3
- Compatible to SOD-128 package case outline
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

MECHANICAL DATA

Case: SlimSMAW (DO-221AD)

Molding compound meets UL 94 V-0 flammability rating
 Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

H3 and HM3 suffix meets JESD 201 class 2 whisker test

Polarity: color band denotes cathode end

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	VSS8D3M12	UNIT
Device marking code		3M12	
Maximum repetitive peak reverse voltage	V_{RRM}	120	V
Maximum average forward rectified current (fig.1)	$I_{F(AV)}^{(1)}$	3	A
	$I_{F(AV)}^{(2)}$	2	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	60	A
Operating junction temperature range	$T_J^{(3)}$	-40 to +175	°C
Storage temperature range	T_{STG}	-55 to +175	

Notes

(1) Mounted on 30 mm x 30 mm AL PCB pad area

(2) Free air, mounted on recommended copper pad area

(3) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$



ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 1.5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.61	-	V
	$I_F = 3\text{ A}$			0.75	0.83	
	$I_F = 1.5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.52	-	
	$I_F = 3\text{ A}$			0.61	0.69	
Reverse current	$V_R = 90\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	0.01	-	mA
		$T_A = 125\text{ }^\circ\text{C}$		0.5	-	
	$V_R = 120\text{ V}$	$T_A = 25\text{ }^\circ\text{C}$		-	0.3	
		$T_A = 125\text{ }^\circ\text{C}$		1	4	
Typical junction capacitance	4.0 V, 1 MHz		C_J	310	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
(2) Pulse test: pulse width $\leq 5\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise specified)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	120	150	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	12	15	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
(2) Thermal resistance junction-to-ambient to follow JEDEC[®] 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
(3) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
VSS8D3M12-M3/H	0.033	H	3500	7" diameter plastic tape and reel
VSS8D3M12-M3/I	0.033	I	14 000	13" diameter plastic tape and reel
VSS8D3M12HM3/H ⁽¹⁾	0.033	H	3500	7" diameter plastic tape and reel
VSS8D3M12HM3/I ⁽¹⁾	0.033	I	14 000	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

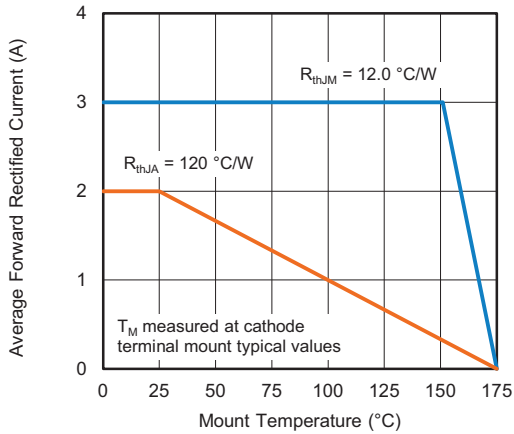


Fig. 1 - Maximum Forward Current Derating Curve

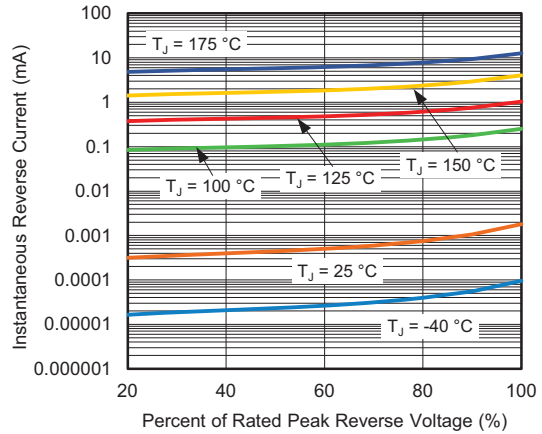


Fig. 4 - Typical Reverse Leakage Characteristics



Fig. 2 - Forward Power Loss Characteristics

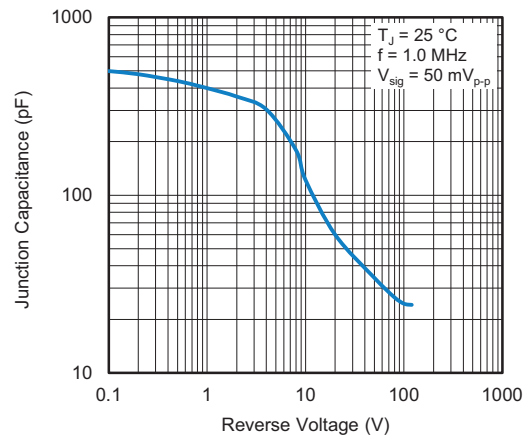


Fig. 5 - Typical Junction Capacitance

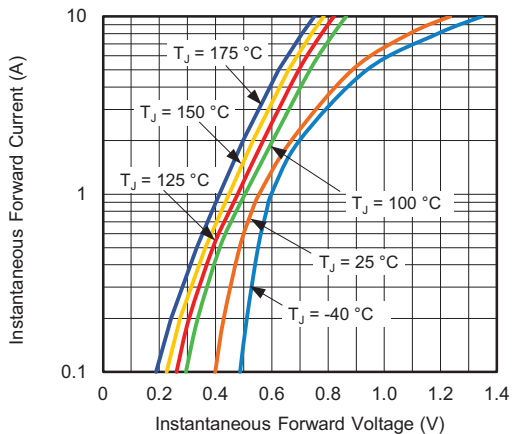


Fig. 3 - Typical Instantaneous Forward Characteristics

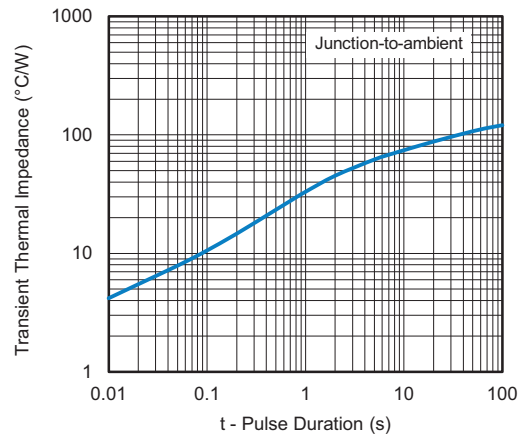


Fig. 6 - Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SlimSMAW (DO-221AD)



Mounting pad layout



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